

# Power Logic Level MOSFETs

## N-Channel Logic Level

### Power Field-Effect Transistors ( $L^2$ FET)

2 and 4 A, 50 V — 60 V  
 $r_{DS(on)}$ : 0.6 $\Omega$  and 0.75 $\Omega$

**Features:**

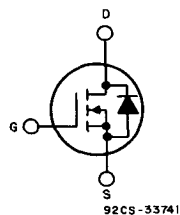
- Design optimized for 5 volt gate drive
- Can be driven directly from Q-MOS, N-MOS, TTL Circuits
- Compatible with automotive drive requirements
- SOA is power-dissipation limited
- Nanosecond switching speeds
- Linear transfer characteristics
- High input impedance
- Majority carrier device

The RFL2N05L and RFL2N06L and the RFP4N05L and RFP4N06L\* are N-channel enhancement-mode silicon-gate power field-effect transistors designed for applications such as switching regulators, switching converters, motor drivers, relay drivers, and drivers for high-power bipolar switching transistors requiring high speed and low gate-drive power. These types can be operated directly from integrated circuits.

The RFL-series types are supplied in the JEDEC TO-205AF metal package and the RFP-series types in the JEDEC TO-220AB plastic package.

\*The RFL and RFP series were formerly RCA developmental numbers TA9520 and TA9521, respectively.

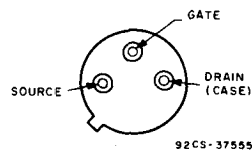
TERMINAL DIAGRAM



**N-CHANNEL ENHANCEMENT MODE**

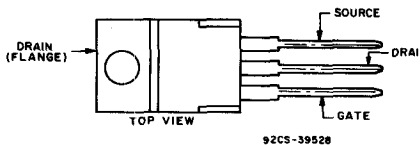
TERMINAL DESIGNATIONS

RFL2N05L  
RFL2N06L



RFP4N05L  
RFP4N06L

JEDEC TO-205AF



JEDEC TO-220AB

**MAXIMUM RATINGS, Absolute-Maximum Values ( $T_c = 25^\circ C$ ):**

	RFL2N05L	RFL2N06L	RFP4N05L	RFP4N06L		
DRAIN-SOURCE VOLTAGE .....	$V_{DSS}$	50	60	50	60	V
DRAIN-GATE VOLTAGE ( $R_{GS} = 1 M\Omega$ ) .....	$V_{DGR}$	50	60	50	60	V
GATE-SOURCE VOLTAGE .....	$V_{GS}$	$\pm 10$				V
DRAIN CURRENT, RMS Continuous .....	$I_D$	2	2	4	4	A
Pulsed .....	$I_{DM}$	$10$				A
POWER DISSIPATION @ $T_c = 25^\circ C$ .....	$P_T$	8.33	8.33	25	25	W
Derate above $T_c = 25^\circ C$ .....		0.0667	0.0667	0.2	0.2	W/ $^\circ C$
OPERATING AND STORAGE						
TEMPERATURE .....	$T_j, T_{stg}$	$-55$ to $+150$				$^\circ C$

RFL2N05L, RFL2N06L, RFP4N05L, RFP4N06L

ELECTRICAL CHARACTERISTICS, At Case Temperature ( $T_c = 25^\circ\text{C}$ ) unless otherwise specified

CHARACTERISTIC	SYMBOL	TEST CONDITIONS	LIMITS				UNITS
			RFL2N05L RFP4N05L		RFL2N06L RFP4N06L		
			MIN.	MAX.	MIN.	MAX.	
Drain-Source Breakdown Voltage	$BV_{DSS}$	$I_D = 1\text{ mA}$ $V_{GS} = 0$	50	—	60	—	V
Gate-Threshold Voltage	$V_{GS(th)}$	$V_{GS} = V_{DS}$ $I_D = 2\text{ mA}$	1	2	1	2	V
Zero-Gate Voltage Drain Current	$I_{DSS}$	$V_{DS} = 40\text{ V}$ $V_{DS} = 50\text{ V}$	—	1	—	—	$\mu\text{A}$
		$T_c = 125^\circ\text{C}$ $V_{DS} = 40\text{ V}$ $V_{DS} = 50\text{ V}$	—	50	—	—	
			—	—	—	50	
			—	—	—	50	
Gate-Source Leakage Current	$I_{GSS}$	$V_{GS} = \pm 10\text{ V}$ $V_{DS} = 0$	—	100	—	100	nA
Drain-Source On Voltage	$V_{DS(on)}^a$	$I_D = 1\text{ A}$ $V_{GS} = 5\text{ V}$	—	.8	—	.8	V
		$I_D = 2\text{ A}$ $V_{GS} = 5\text{ V}$	—	2.0	—	2.0	
		$I_D = 4\text{ A}$ $V_{GS} = 7.5\text{ V}$	—	4.8	—	4.8	
			—	—	—	—	
Static Drain-Source On Resistance	$r_{DS(on)}^a$	$I_D = 1\text{ A}$   RFP	—	0.6	—	0.6	$\Omega$
		$V_{GS} = 5\text{ V}$   RFL	—	0.75	—	0.75	
Forward Transconductance	$g_{fs}^a$	$V_{DS} = 10\text{ V}$ $I_D = 1\text{ A}$	800	—	800	—	mmho
Input Capacitance	$C_{iss}$	$V_{DS} = 25\text{ V}$ $V_{GS} = 0\text{ V}$ $f = 1\text{ MHz}$	—	225	—	225	pF
Output Capacitance	$C_{oss}$		—	100	—	100	
Reverse-Transfer Capacitance	$C_{rss}$		—	40	—	40	
Turn-On Delay Time	$t_{d(on)}$	$V_{DD} = 30\text{ V}$ $I_D = 1\text{ A}$ $R_{\theta gen} = \infty$ $R_{gs} = 6.25\ \Omega$ $V_{GS} = 5\text{ V}$	10(typ)	20	10(typ)	20	ns
Rise Time	$t_r$		65(typ)	130	65(typ)	130	
Turn-Off Delay Time	$t_{d(off)}$		20(typ)	40	20(typ)	40	
Fall Time	$t_f$		30(typ)	60	30(typ)	60	
Thermal Resistance Junction-to-Case	$R\theta_{JC}$	RFL2N05L, RFL2N06L	—	15	—	15	$^\circ\text{C/W}$
		RFP4N05L, RFP4N06L	—	5	—	5	

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SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS

CHARACTERISTIC	SYMBOL	TEST CONDITIONS	LIMITS				UNITS
			RFL2N05L RFP4N05L		RFL2N06L RFP4N06L		
			MIN.	MAX.	MIN.	MAX.	
Diode Forward Voltage	$V_{SD}^a$	$I_{SO} = 1\text{ A}$	—	1.4	—	1.4	V
Reverse Recovery Time	$t_{rr}$	$I_F = 2\text{ A}$ , $dI_F/dt = 100\text{ A}/\mu\text{s}$	150 (typ.)		150 (typ.)		ns

<sup>a</sup> Pulse Test: Width  $\leq 300\ \mu\text{s}$ , Duty cycle  $\leq 2\%$ .

RFL2N05L, RFL2N06L, RFP4N05L, RFP4N06L

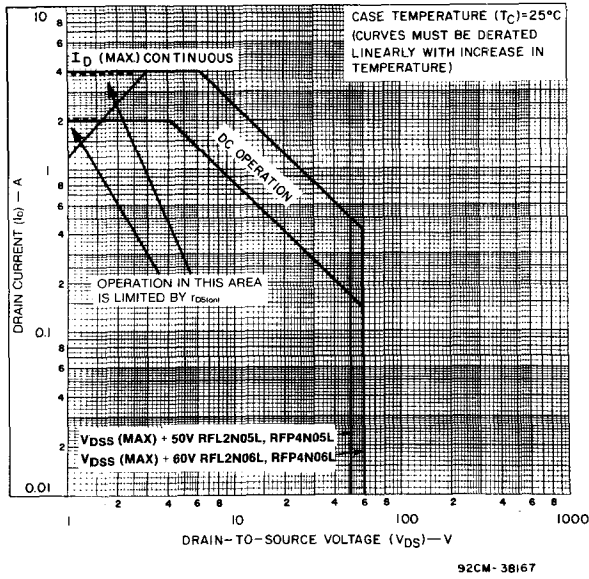


Fig. 1 - Maximum operating areas for all types.

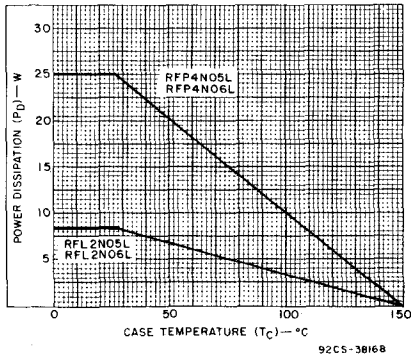


Fig. 2 - Power dissipation vs. case temperature derating curve for all types.

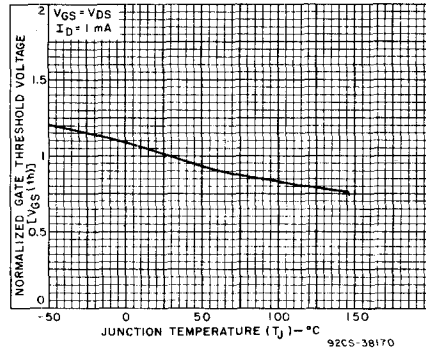


Fig. 3 - Typical normalized gate threshold voltage as a function of junction temperature for all types.

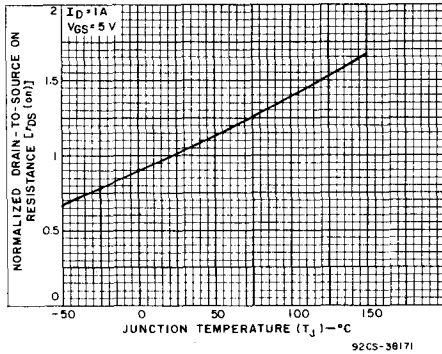


Fig. 4 - Normalized drain-to-source on resistance vs. junction temperature for all types.

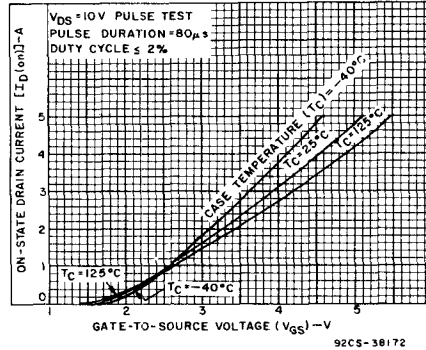


Fig. 5 - Typical transfer characteristics for all types.

RFL2N05L, RFL2N06L, RFP4N05L, RFP4N06L

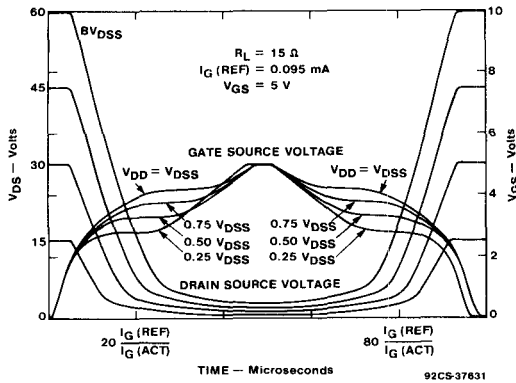


Fig. 6 - Normalized switching waveforms for constant gate-current. Refer to RCA application notes AN-7254 and AN-7260.

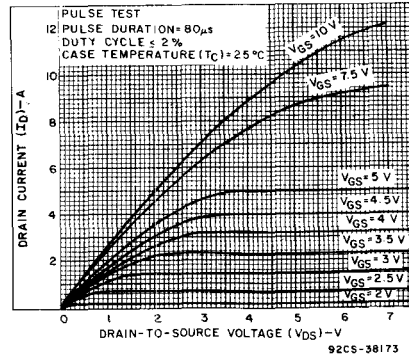


Fig. 7 - Typical saturation characteristics for all types.

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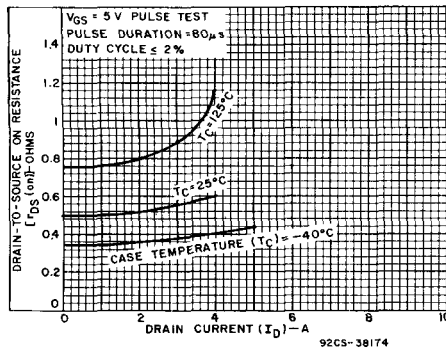


Fig. 8 - Typical drain-to-source on resistance as a function of drain current for all types.

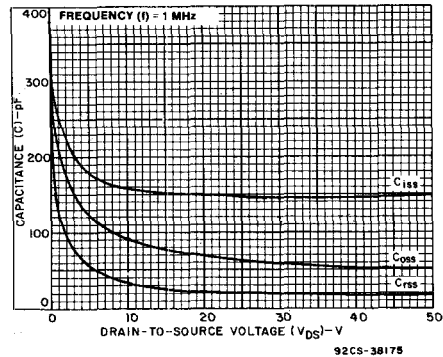


Fig. 9 - Capacitance as a function of drain-to-source voltage for all types.

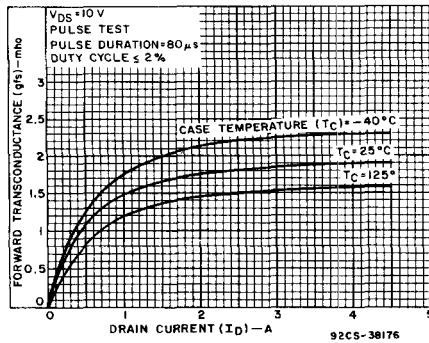


Fig. 10 - Typical forward transconductance as a function of drain current for all types.

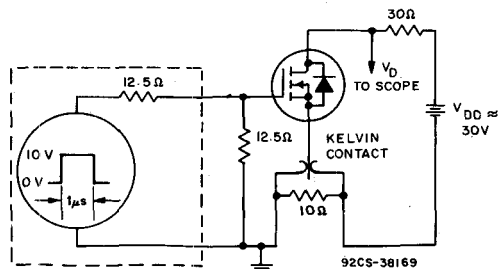


Fig. 11 - Switching Time Test Circuit.